

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a built-up printed circuit board with stacked micro via-holes, each of which is provided for interconnection between layers in the printed circuit board, and in each of which a filling material, such as liquefied resin or conductive paste, is filled using a poly screen of a general screen printing machine, and a method for manufacturing the same. The method comprises the steps of (a) forming a first via-hole through a first laminated copper sheet by means of a laser drill, (b) forming a first plated layer on the first via-hole and the first laminated copper sheet, (c) filling the first plated via-hole with a via-hole filling material, (d) forming a second plated layer on the first filled via-hole and the first plated layer to cover the first filled via-hole, (e) forming a second plated layer on the first filled via-hole and the first plated layer to cover the first filled via-hole, and (f) disposing a second laminated copper sheet on the second plated layer. The steps (a) to (e) are repeated to form a second via-hole. The via-hole filling material is liquefied insulating resin or conductive paste. The via-hole filling material is filled only in each of the via-holes by a general screen printing process, thereby reducing the amount of consumption of the liquefied insulating resin or the conductive paste. Furthermore, the

built-up printed circuit board according to the present invention can be manufactured using the existing production facilities, thereby reducing the cost of manufacturing the printed circuit board.